



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-15
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
USB6B1RL	HDO7*USB6V0C	A	SHENZHEN B/E	2016-09-15
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAuAg	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9-6-1.75	8	GULL WING	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HDO7*USB6VOC					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.309	mg	supplier	die	Silicon (Si)	7440-21-3		2.195	mg	950628	27438
				supplier	metallization	Aluminium (Al)	7429-90-5		0.036	mg	15591	450
				supplier	Passivation	Silicon Oxide	7631-86-9		0.012	mg	5197	150
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.012	mg	5197	150
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	433	13
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1732	50
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.019	mg	8229	232
				supplier	polymer die coating	Proprietary			0.030	mg	12993	375
				supplier	alloy	Copper (Cu)	7440-50-8		29.710	mg	997114	371375
Leadframe	Copper & its alloys	29.796	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.014	mg	470	175
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.025	mg	837	313
				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1477	550
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	34	13
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	34	13
				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	34	13
				supplier	metallization	Silver (Ag)	7440-22-4		0.936	mg	910506	11700
Die attach	Other Organic Materials	1.028	mg	supplier	glue or tape	acrylate	Proprietary		0.051	mg	49611	638
				supplier	glue or tape	Methacrylate	Proprietary		0.041	mg	39883	513
				supplier	wire	Copper (Cu)	7440-50-8		0.196	mg	1000000	2450
Bonding wires	Other inorganic materials	0.196	mg	supplier	wire	Silica, vitreous	60676-86-0		40.417	mg	865998	505213
				supplier	mold compound	Epoxy Resin	25068-98-6		3.500	mg	74993	43750
Encapsulation	Other Organic Materials	46.671	mg	supplier	mold compound	Phenol Resin	29690-82-2		2.334	mg	50010	29175
				supplier	mold compound	Carbon black	1333-86-4		0.233	mg	4992	2913
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.187	mg	4007	2338
				supplier	mold compound							